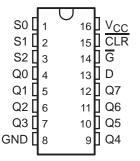
- 8-Bit Parallel-Out Storage Register Performs Serial-to-Parallel Conversion With Storage
- Asynchronous Parallel Clear
- Active-High Decoder
- Enable/Disable Input Simplifies Expansion
- Expandable for n-Bit Applications
- Four Distinct Functional Modes
- Package Options Include Plastic Small-Outline (D) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) 300-mil DIPs

### description

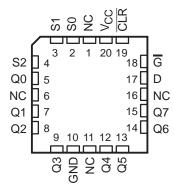
These 8-bit addressable latches are designed for general-purpose storage applications in digital systems. Specific uses include working registers, serial-holding registers, and active-high decoders or demultiplexers. They are multifunctional devices capable of storing single-line data in eight addressable latches and being a 1-of-8 decoder or demultiplexer with active-high outputs.

Four distinct modes of operation are selectable by controlling the clear  $(\overline{CLR})$  and enable  $(\overline{G})$  inputs as shown in the function table. In the addressable-latch mode, data at the data-in terminal is written into the addressed latch. The

SN54ALS259 . . . J PACKAGE SN74ALS259 . . . D OR N PACKAGE (TOP VIEW)



SN54ALS259 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

addressed latch follows the data input with all unaddressed latches remaining in their previous states. In the memory mode, all latches remain in their previous states and are unaffected by the data or address inputs. To eliminate the possibility of entering erroneous data in the latches,  $\overline{G}$  should be held high (inactive) while the address lines are changing. In the 1-of-8 decoding or demultiplexing mode, the addressed output follows the level of the D input with all other outputs low. In the clear mode, all outputs are low and unaffected by the address and data inputs.

The SN54ALS259 is characterized for operation over the full military temperature range of  $-55^{\circ}$ C to 125°C. The SN74ALS259 is characterized for operation from 0°C to 70°C.

#### **Function Tables**

#### **FUNCTION**

INPU	JTS	OUTPUT OF	EACH					
CLR	G	ADDRESSED LATCH	OTHER OUTPUT	FUNCTION				
Н	L	D	Q <sub>iO</sub>	Addressable latch				
Н	Н	Q <sub>iO</sub>	Q <sub>iO</sub>	Memory				
L	L	D	L	8-line demultiplexer				
L	Н	L	L	Clear				

D = the level at the data input.

 $Q_{iO}$  = the level of  $Q_i$  (i = Q, 1, . . . 7 as appropriate) before the indicated steady-state input conditions were established.

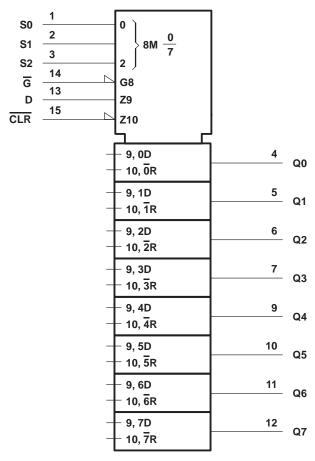


## **Function Tables (Continued)**

### LATCH SELECTION

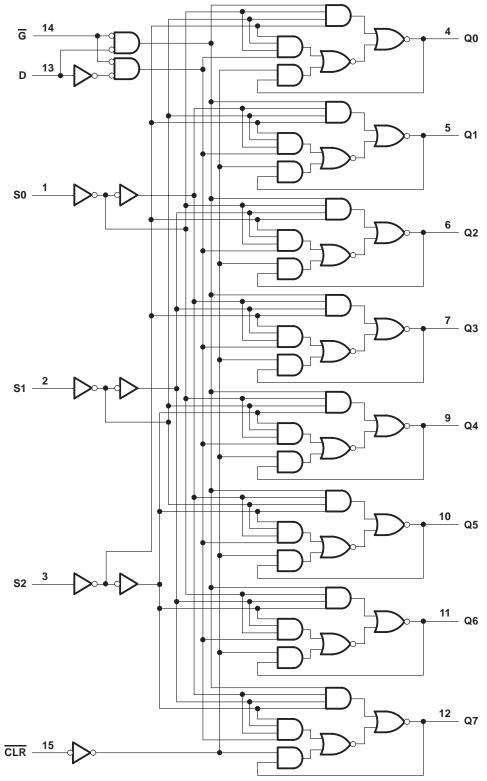
SEL	ECT INP	UTS	LATCH
S2	S1	S0	ADDRESSED
L	L	L	0
L	L	Н	1
L	Н	L	2
L	Н	Н	3
Н	L	L	4
Н	L	Н	5
Н	Н	L	6
Н	Н	Н	7

# logic symbol†



<sup>&</sup>lt;sup>†</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the D, J, and N packages.

# logic diagram (positive logic)



Pin numbers shown are for the D, J, and N packages.



SDAS217A - DECEMBER 1982 - REVISED DECEMBER 1994

# absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V <sub>CC</sub>		 	7 V
Input voltage, V <sub>I</sub>		 	7 V
Operating free-air temperature range, T <sub>A</sub> :	SN54ALS259	 	-55°C to 125°C
	SN74ALS259	 	0°C to 70°C
Storage temperature range			_65°C to 150°C

### recommended operating conditions

			SN	54ALS2	59	SN	74ALS2	59		
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT	
Vcc	Supply voltage		4.5	5	5.5	4.5	5	5.5	V	
VIH	High-level input voltage		2			2			V	
VIL	Low-level input voltage			0.7			0.8	V		
IOH	High-level output current			-0.4			-0.4	mA		
loL	Low-level output current				4			8	mA	
	Pulsa donetta	G low	20			15				
t <sub>W</sub>	Pulse duration	CLR low	10			10			ns	
	Outure Cons	Data before G↑	20			15				
<sup>t</sup> su	Setup time	Address before G↑	20			15			ns	
	11.110	Data after G↑	0			0				
th	Hold time	Address after G↑	0			0			ns	
T <sub>A</sub>	Operating free-air temperature		-55		125	0		70	°C	

### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

242445752		TEST CONDITIONS			59	SN74ALS259			
PARAMETER	TEST C	ONDITIONS	MIN	TYP‡	MAX	MIN	TYP‡	MAX	UNIT
VIK	$V_{CC} = 4.5 V,$	I <sub>I</sub> = –18 mA			-1.5			-1.5	V
Voн	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V},$	$I_{OH} = -0.4 \text{ mA}$	V <sub>CC</sub> -2	)		V <sub>CC</sub> -2	<u>)</u>		>
V	V 45.V	$I_{OL} = 4 \text{ mA}$		0.25	0.4		0.25	0.4	V
V <sub>OL</sub>	V <sub>CC</sub> = 4.5 V	$I_{OL} = 8 \text{ mA}$					0.35	0.5	V
lį	$V_{CC} = 5.5 V$ ,	V <sub>I</sub> = 7 V			0.1			0.1	mA
lН	$V_{CC} = 5.5 V,$	V <sub>I</sub> = 2.7 V			20			20	μΑ
I <sub>I</sub> L	$V_{CC} = 5.5 V,$	V <sub>I</sub> = 0.4 V			-0.1			-0.1	mA
ΙΟ§	$V_{CC} = 5.5 V,$	V <sub>O</sub> = 2.25 V	-20		-112	-30		-112	mA
ICC	V <sub>CC</sub> = 5.5 V	_		14	22		14	22	mA

<sup>‡</sup> All typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ .



<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

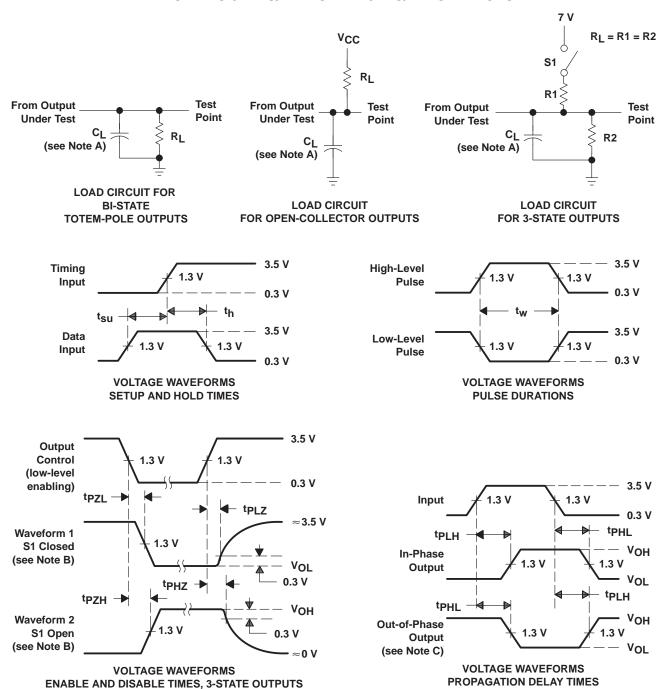
<sup>§</sup> The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, IOS.

# switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>C</sub> C <sub>L</sub> R <sub>L</sub> T <sub>A</sub>	UNIT			
			SN54A	LS259	SN74ALS259		
			MIN	MAX	MIN	MAX	
<sup>t</sup> PHL	CLR	Any Q	2	15	2	12	ns
<sup>t</sup> PLH	Data	A O	4	22	4	19	
<sup>t</sup> PHL	Data	Any Q	2	15	2	12	ns
<sup>t</sup> PLH	A dalue e e	A O	4	26	4	22	
<sup>t</sup> PHL	Address	Any Q	2	15	2	12	ns
<sup>t</sup> PLH	Execute	Any Q	4	22	4	20	ns
<sup>t</sup> PHL	LACCULE	Ally Q	2	16	2	13	115

<sup>†</sup> For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

# PARAMETER MEASUREMENT INFORMATION SERIES 54ALS/74ALS AND 54AS/74AS DEVICES



- NOTES: A. C<sub>L</sub> includes probe and jig capacitance.
  - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
  - C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
  - D. All input pulses have the following characteristics: PRR  $\leq$  1 MHz,  $t_{\Gamma} = t_{f} = 2$  ns, duty cycle = 50%.
  - E. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms



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#### PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
5962-8874101EA	ACTIVE	CDIP	J	16	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8874101EA SNJ54ALS259J	Samples
SN54ALS259J	ACTIVE	CDIP	J	16	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54ALS259J	Samples
SN74ALS259DR	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS259	Samples
SN74ALS259N	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS259N	Samples
SNJ54ALS259J	ACTIVE	CDIP	J	16	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8874101EA SNJ54ALS259J	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

# **PACKAGE OPTION ADDENDUM**

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#### OTHER QUALIFIED VERSIONS OF SN54ALS259, SN74ALS259:

Catalog: SN74ALS259

Military: SN54ALS259

NOTE: Qualified Version Definitions:

Catalog - TI's standard catalog product

• Military - QML certified for Military and Defense Applications

# **PACKAGE MATERIALS INFORMATION**

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### TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	U	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALS259DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1

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#### \*All dimensions are nominal

	Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)	
ı	SN74ALS259DR	SOIC	D	16	2500	340.5	336.1	32.0	

# **PACKAGE MATERIALS INFORMATION**

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### **TUBE**



#### \*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN74ALS259N	N	PDIP	16	25	506	13.97	11230	4.32
SN74ALS259N	N	PDIP	16	25	506	13.97	11230	4.32

# D (R-PDS0-G16)

## PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



# 14 LEADS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

# N (R-PDIP-T\*\*)

# PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



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